

Chiara Mariotti

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/291898/publications.pdf>

Version: 2024-02-01

20
papers

383
citations

759233

12
h-index

1058476

14
g-index

20
all docs

20
docs citations

20
times ranked

452
citing authors

#	ARTICLE	IF	CITATIONS
1	No Battery Required: Perpetual RFID-Enabled Wireless Sensors for Cognitive Intelligence Applications. IEEE Microwave Magazine, 2013, 14, 66-77.	0.8	74
2	Low-Power Frequency Doubler in Cellulose-Based Materials for Harmonic RFID Applications. IEEE Microwave and Wireless Components Letters, 2014, 24, 896-898.	3.2	37
3	High-Performance RF Devices and Components on Flexible Cellulose Substrate by Vertically Integrated Additive Manufacturing Technologies. IEEE Transactions on Microwave Theory and Techniques, 2017, 65, 62-71.	4.6	33
4	Development of Low Cost, Wireless, Inkjet Printed Microfluidic RF Systems and Devices for Sensing or Tunable Electronics. IEEE Sensors Journal, 2015, 15, 3156-3163.	4.7	32
5	24 GHz Patch antenna array on cellulose-based materials for green wireless internet applications. IET Science, Measurement and Technology, 2014, 8, 342-349.	1.6	26
6	Demonstration of a chipless harmonic tag working as crack sensor for electronic sealing applications. Wireless Power Transfer, 2015, 2, 78-85.	1.1	26
7	Smart Hardware for Smart Objects: Microwave Electronic Circuits to Make Objects Smart. IEEE Microwave Magazine, 2018, 19, 48-68.	0.8	26
8	24 GHz Single-Balanced Diode Mixer Exploiting Cellulose-Based Materials. IEEE Microwave and Wireless Components Letters, 2013, 23, 596-598.	3.2	25
9	State-of-the-Art Inkjet-Printed Metal-Insulator-Metal (MIM) Capacitors on Silicon Substrate. IEEE Microwave and Wireless Components Letters, 2015, 25, 13-15.	3.2	20
10	Silicon Taper Based DSB -Band Chip to Waveguide Interconnect for Millimeter-Wave Systems. IEEE Microwave and Wireless Components Letters, 2017, 27, 1092-1094.	3.2	16
11	A 1.2 V, 0.9 mW UHF VCO Based on Hairpin Resonator in Paper Substrate and Cu Adhesive Tape. IEEE Microwave and Wireless Components Letters, 2013, 23, 214-216.	3.2	14
12	Communication and Sensing Circuits on Cellulose. Journal of Low Power Electronics and Applications, 2015, 5, 151-164.	2.0	14
13	24-GHz CW radar front-ends on cellulose-based substrates: A new technology for low-cost applications. , 2015, , .		10
14	Demonstration of +100-GHz Interconnects in eWLB Packaging Technology. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 1406-1414.	2.5	9
15	A novel compact harmonic RFID sensor in paper substrate based on a variable attenuator and nested antennas. , 2016, , .		8
16	A non-galvanic D-band MMIC-to-waveguide transition using eWLB packaging technology. , 2017, , .		8
17	“Energy evaporation”: The new concept of indoor systems for WPT and EH embedded into the floor. , 2015, , .		4
18	Low-Frequency Excess Noise Ratio Approximation for Avalanche Noise Diodes. IEEE Microwave and Wireless Components Letters, 2019, 29, 601-603.	3.2	1

#	ARTICLE	IF	CITATIONS
19	Dual-frequency antennas embedded into the floor for efficient RF “energy evaporation”, 2015, , .		0
20	High Volume Silicon Based Technologies for Heterogeneous THz Platforms: From the Silicon to the Board. , 2018, , .		0